

# Multilayer Ceramic Chip Capacitors

## CGB2A1X6S0G105K033BC



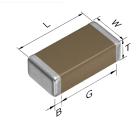






## **TDK item description** CGB2A1X6S0G105KT\*\*\*\*

Applications	Commercial Grade
Feature	LowT Low Profile
Series	CGB2(1005) [EIA 0402]
Status	Production



Size	
Length(L)	1.00mm ±0.05mm
Width(W)	0.50mm ±0.05mm
Thickness(T)	0.30mm ±0.03mm
Terminal Width(B)	0.10mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern (PA)	0.30mm to 0.50mm
Recommended Land Pattern (PB)	0.35mm to 0.45mm
Recommended Land Pattern (PC)	0.40mm to 0.60mm

Electrical Characteristics		
Capacitance	1μF ±10%	
Rated Voltage	4VDC	
Temperature Characteristic	X6S(±22%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	100ΜΩ	

Other	
Soldering Method	Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	10000pcs

<sup>!</sup> Images are for reference only and show exemplary products.

<sup>!</sup> This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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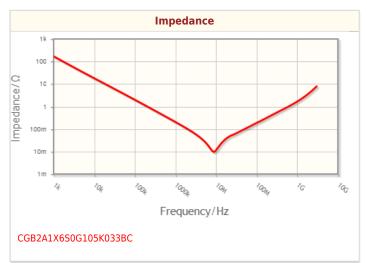


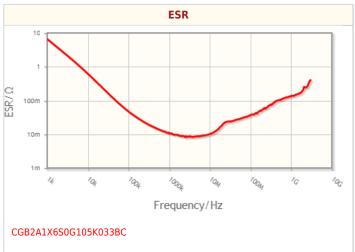


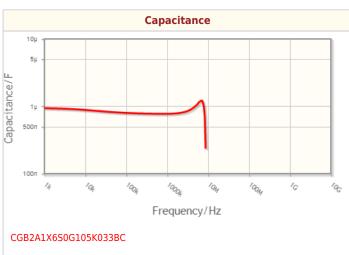


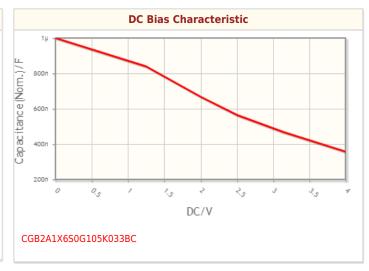


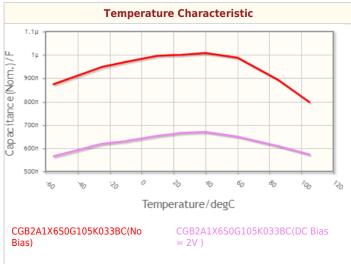
# Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

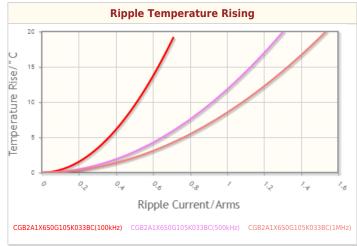












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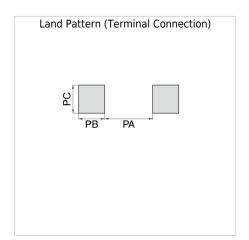








# **Associated Images**



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